



Statement of Materials, Construction

LEAD-FREE -- 20L-SOICW -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.15709	Cu	7440-50-8	0.15271	28.22875	97.213
				Fe	7439-89-6	0.00369	0.68239	2.35
				Pb	7439-92-1	0.00004	0.00900	0.03
				P	7723-14-0	0.00013	0.02381	0.082
				Ag	7740-22-4	0.00031	0.05808	0.2
				Zn	7440-66-6	0.00020	0.03630	0.125
2	Die	Silicon Chip	0.00344	Si	7440-21-3	0.00342	0.63270	99.5
3	Die attach material	Conductive Epoxy	0.00235	Epoxy resin (5-25)	Proprietary	0.00035	0.06516	15
				Silver (70-85)	7440-22-4	0.00187	0.34535	79.5
				Aromatic Amine (1-10)	Proprietary	0.00013	0.02389	5.5
4	Wire	Gold	0.00120	Au	7440-57-5	0.00120	0.22180	99.99
5	Lead Finish	Tin	0.0059	Sn	7440-31-5	0.00590	1.09061	100
6	Encapsulation	Epoxy Resin	0.371	Fused Silica	60676-86-0	0.31424	58.08662	84.7
				Epoxy resin	29690-82-2	0.02412	4.45765	6.5
				Phenol Resin	9003-35-4	0.01484	2.74317	4
				Brominated Epoxy Resin	40039-93-8	0.00928	1.71448	2.5
				Carbon Black	1333-86-4	0.00111	0.20574	0.3
				Antimony trioxide	1309-64-4	0.00742	1.37158	2
Total Package weight			0.54098					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (aximum Allowable Limit (wt %)	
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%